## 2SD2259

### Silicon NPN epitaxial planar type

#### For low-frequency amplification

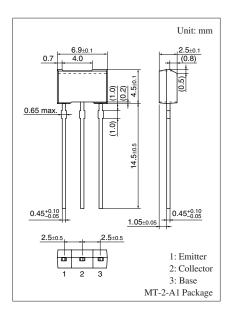
#### ■ Features

- High forward current transfer ratio h<sub>FE</sub>
- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Allowing supply with the radial taping

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | 20          | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 20          | V    |  |
| Emitter-base voltage (Collector open) | $V_{EBO}$        | 15          | V    |  |
| Collector current                     | $I_C$            | 0.7         | A    |  |
| Peak collector current                | $I_{CP}$         | 1.5         | A    |  |
| Collector power dissipation *         | P <sub>C</sub>   | 1           | W    |  |
| Junction temperature                  | $T_{j}$          | 150         | °C   |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +150 | °C   |  |

Note) \*: Printed circuit board: Copper foil area of 1  $\rm cm^2$  or more, and the board thickness of 1.7 mm for the collector portion



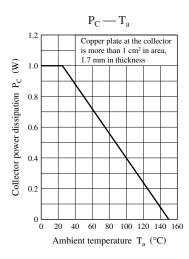
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

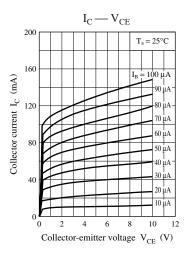
| Parameter                                    | Symbol               | Conditions   | Min   | Тур  | Max  | Unit |
|--|----------------------|--|-------|------|------|------|
| Collector-base voltage (Emitter open)        | V <sub>CBO</sub>     | $I_C = 10 \mu\text{A},  I_E = 0$                                   | 20    |      |      | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>     | $I_C = 1 \text{ mA}, I_B = 0$                                      | 20    |      |      | V    |
| Emitter-base voltage (Collector open)        | $V_{EBO}$            | $I_E = 10 \ \mu A, I_C = 0$  | 15    |      |      | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$            | $V_{CB} = 15 \text{ V}, I_{E} = 0$                                 |       |      | 1    | μΑ   |
| Collector-emitter cutoff current (Base open) | $I_{CEO}$            | $V_{CE} = 15 \text{ V}, I_{B} = 0$                                 |       |      | 10   | μΑ   |
| Forward current transfer ratio *             | h <sub>FE</sub>      | $V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$                    | 1 000 |      | 2500 | _    |
| Collector-emitter saturation voltage *       | V <sub>CE(sat)</sub> | $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$                        |       | 0.15 | 0.40 | V    |
| Transition frequency                         | $f_T$                | $V_{CB} = 20 \text{ V}, I_E = -20 \text{ mA}, f = 200 \text{ MHz}$ |       | 55   |      | MHz  |
| Collector output capacitance                 | C <sub>ob</sub>      | $V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$              |       | 10   | 15   | pF   |
| (Common base, input open circuited)          |                      |  |       |      |      |      |

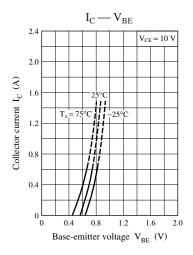
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

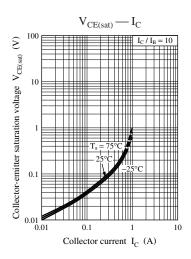
2. \*: Pulse measurement

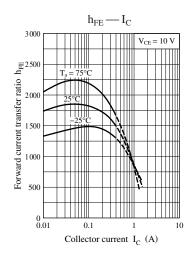
## **Panasonic**

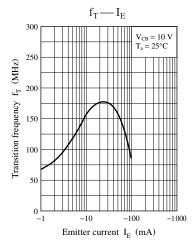


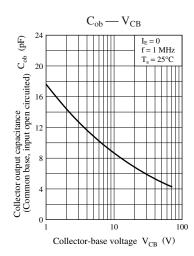












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